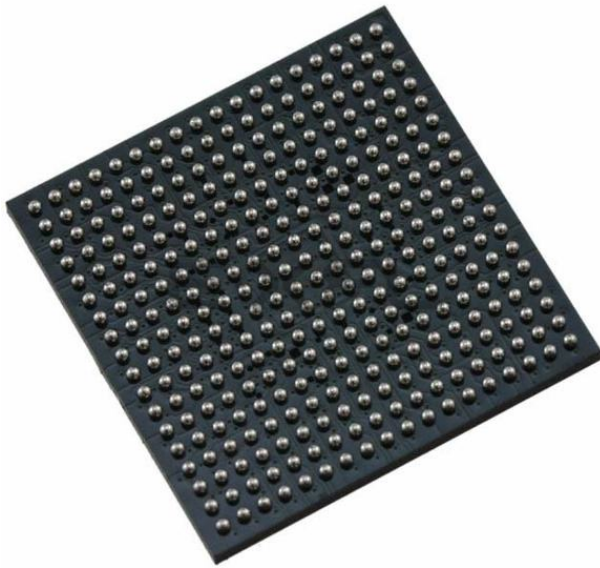




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	285
Number of Logic Elements/Cells	2280
Total RAM Bits	28262
Number of I/O	271
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	324-LBGA
Supplier Device Package	324-FTBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo2280e-3ft324i

Features

■ Non-volatile, Infinitely Reconfigurable

- Instant-on – powers up in microseconds
- Single chip, no external configuration memory required
- Excellent design security, no bit stream to intercept
- Reconfigure SRAM based logic in milliseconds
- SRAM and non-volatile memory programmable through JTAG port
- Supports background programming of non-volatile memory

■ Sleep Mode

- Allows up to 100x static current reduction

■ TransFR™ Reconfiguration (TFR)

- In-field logic update while system operates

■ High I/O to Logic Density

- 256 to 2280 LUT4s
- 73 to 271 I/Os with extensive package options
- Density migration supported
- Lead free/RoHS compliant packaging

■ Embedded and Distributed Memory

- Up to 27.6 Kbits sysMEM™ Embedded Block RAM
- Up to 7.7 Kbits distributed RAM
- Dedicated FIFO control logic

■ Flexible I/O Buffer

- Programmable sysIO™ buffer supports wide range of interfaces:
 - LVCMOS 3.3/2.5/1.8/1.5/1.2
 - LVTTTL
 - PCI
 - LVDS, Bus-LVDS, LVPECL, RSDS

■ sysCLOCK™ PLLs

- Up to two analog PLLs per device
- Clock multiply, divide, and phase shifting

■ System Level Support

- IEEE Standard 1149.1 Boundary Scan
- Onboard oscillator
- Devices operate with 3.3V, 2.5V, 1.8V or 1.2V power supply
- IEEE 1532 compliant in-system programming

Introduction

The MachXO is optimized to meet the requirements of applications traditionally addressed by CPLDs and low capacity FPGAs: glue logic, bus bridging, bus interfacing, power-up control, and control logic. These devices bring together the best features of CPLD and FPGA devices on a single chip.

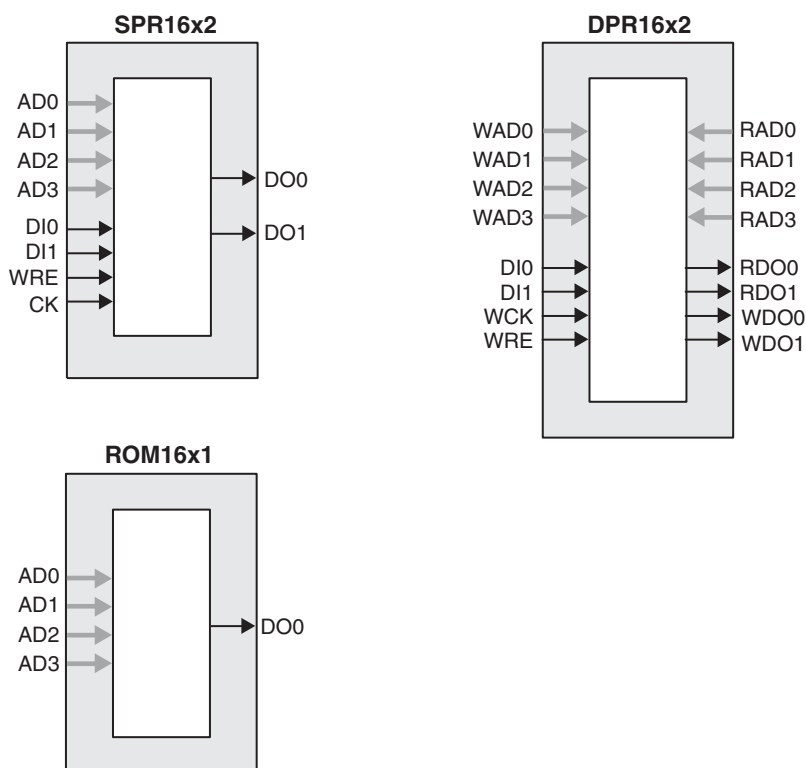
Table 1-1. MachXO Family Selection Guide

Device	LCMX0256	LCMX0640	LCMX01200	LCMX02280
LUTs	256	640	1200	2280
Dist. RAM (Kbits)	2.0	6.1	6.4	7.7
EBR SRAM (Kbits)	0	0	9.2	27.6
Number of EBR SRAM Blocks (9 Kbits)	0	0	1	3
V _{CC} Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
Number of PLLs	0	0	1	2
Max. I/O	78	159	211	271
Packages				
100-pin TQFP (14x14 mm)	78	74	73	73
144-pin TQFP (20x20 mm)		113	113	113
100-ball csBGA (8x8 mm)	78	74		
132-ball csBGA (8x8 mm)		101	101	101
256-ball caBGA (14x14 mm)		159	211	211
256-ball ftBGA (17x17 mm)		159	211	211
324-ball ftBGA (19x19 mm)				271

The devices use look-up tables (LUTs) and embedded block memories traditionally associated with FPGAs for flexible and efficient logic implementation. Through non-volatile technology, the devices provide the single-chip, high-security, instant-on capabilities traditionally associated with CPLDs. Finally, advanced process technology and careful design will provide the high pin-to-pin performance also associated with CPLDs.

The ispLEVER® design tools from Lattice allow complex designs to be efficiently implemented using the MachXO family of devices. Popular logic synthesis tools provide synthesis library support for MachXO. The ispLEVER tools use the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the MachXO device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

Figure 2-18. MachXO2280 Banks

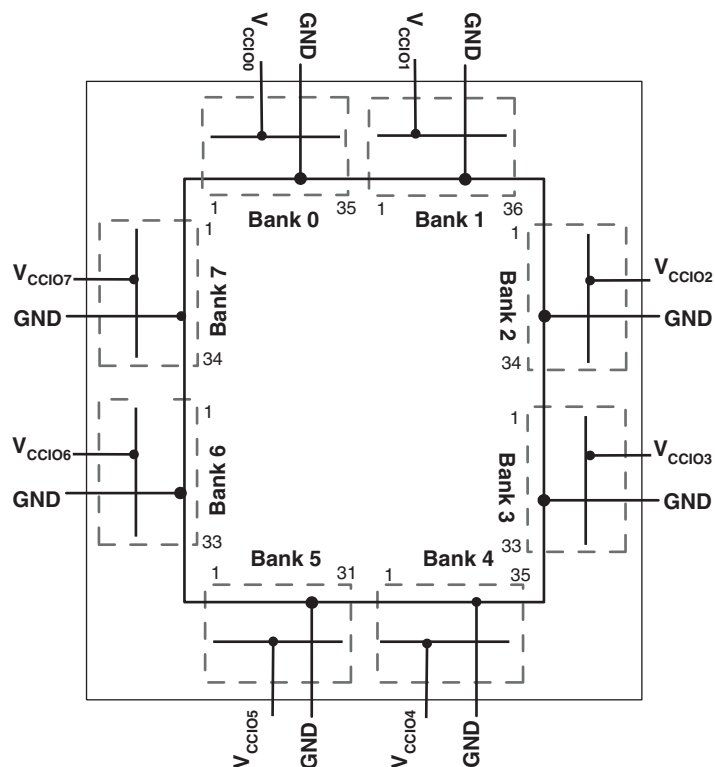
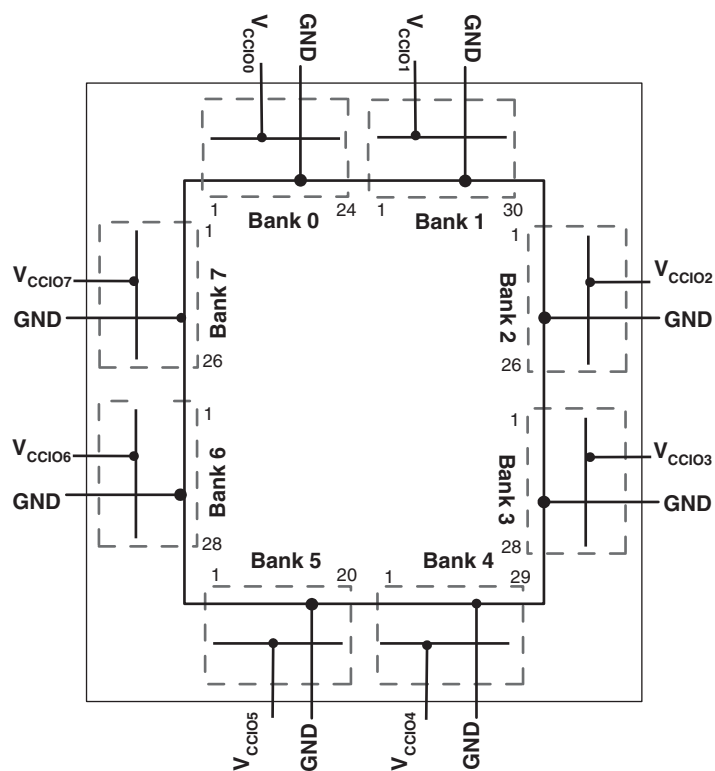


Figure 2-19. MachXO1200 Banks



the system. These capabilities make the MachXO ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The MachXO “C” devices ($V_{CC} = 1.8/2.5/3.3V$) have a sleep mode that allows standby current to be reduced dramatically during periods of system inactivity. Entry and exit to Sleep mode is controlled by the SLEEPN pin.

During Sleep mode, the logic is non-operational, registers and EBR contents are not maintained, and I/Os are tri-stated. Do not enter Sleep mode during device programming or configuration operation. In Sleep mode, power supplies are in their normal operating range, eliminating the need for external switching of power supplies. Table 2-11 compares the characteristics of Normal, Off and Sleep modes.

Table 2-11. Characteristics of Normal, Off and Sleep Modes

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static Icc	Typical <10mA	0	Typical <100uA
I/O Leakage	<10μA	<1mA	<10μA
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	0	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up, along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to VCC is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically, the device enters sleep mode several hundred nanoseconds after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet shows a detailed timing diagram.

Oscillator

Every MachXO device has an internal CMOS oscillator. The oscillator can be routed as an input clock to the clock tree or to general routing resources. The oscillator frequency can be divided by internal logic. There is a dedicated programming bit to enable/disable the oscillator. The oscillator frequency ranges from 18MHz to 26MHz.

Configuration and Testing

The following section describes the configuration and testing features of the MachXO family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All MachXO devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port shares its power supply with one of the VCCIO Banks (MachXO256: V_{CCIO1} ; MachXO640: V_{CCIO2} ; MachXO1200 and MachXO2280: V_{CCIO5}) and can operate with LVCMOS3.3, 2.5, 1.8, 1.5, and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

sysIO Differential Electrical Characteristics

LVDS

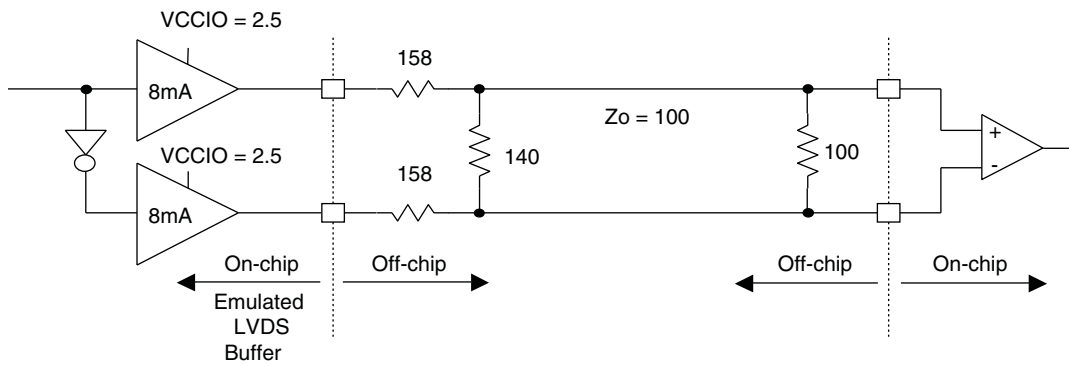
Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage		0	—	2.4	V
V_{THD}	Differential Input Threshold		+/-100	—	—	mV
V_{CM}	Input Common Mode Voltage	$100\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	1.8	V
		$200\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	1.9	V
		$350\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	2.0	V
I_{IN}	Input current	Power on	—	—	+/-10	μA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	$R_T = 100 \text{ Ohm}$	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	$R_T = 100 \text{ Ohm}$	0.9V	1.03	—	V
V_{OD}	Output voltage differential	$(V_{OP} - V_{OM}), R_T = 100 \text{ Ohm}$	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	$(V_{OP} - V_{OM})/2, R_T = 100 \text{ Ohm}$	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	$V_{OD} = 0\text{V}$ Driver outputs shorted	—	—	6	mA

LVDS Emulation

MachXO devices can support LVDS outputs via emulation (LVDS25E), in addition to the LVDS support that is available on-chip on certain devices. The output is emulated using complementary LVCMOS outputs in conjunction with resistors across the driver outputs on all devices. The scheme shown in Figure 3-1 is one possible solution for LVDS standard implementation. Resistor values in Figure 3-1 are industry standard values for 1% resistors.

Figure 3-1. LVDS Using External Resistors (LVDS25E)



Note: All resistors are $\pm 1\%$.

The LVDS differential input buffers are available on certain devices in the MachXO family.

Typical Building Block Function Performance¹

Pin-to-Pin Performance (LVCMOS25 12mA Drive)

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	6.7	ns
4:1 MUX	4.5	ns
16:1 MUX	5.1	ns

Register-to-Register Performance

Function	-5 Timing	Units
Basic Functions		
16:1 MUX	487	MHz
16-bit adder	292	MHz
16-bit counter	388	MHz
64-bit counter	200	MHz
Embedded Memory Functions (1200 and 2280 Devices Only)		
256x36 Single Port RAM	284	MHz
512x18 True-Dual Port RAM	284	MHz
Distributed Memory Functions		
16x2 Single Port RAM	434	MHz
64x2 Single Port RAM	320	MHz
128x4 Single Port RAM	261	MHz
32x2 Pseudo-Dual Port RAM	314	MHz
64x4 Pseudo-Dual Port RAM	271	MHz

1. The above timing numbers are generated using the ispLEVER design tool. Exact performance may vary with device and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

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Derating Logic Timing

Logic Timing provided in the following sections of the data sheet and the ispLEVER design tools are worst case numbers in the operating range. Actual delays may be much faster. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

MachXO External Switching Characteristics¹

Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (Using Global Clock without PLL) ¹									
t _{PD}	Best Case t _{PD} Through 1 LUT	LCMXO256	—	3.5	—	4.2	—	4.9	ns
		LCMXO640	—	3.5	—	4.2	—	4.9	ns
		LCMXO1200	—	3.6	—	4.4	—	5.1	ns
		LCMXO2280	—	3.6	—	4.4	—	5.1	ns
t _{CO}	Best Case Clock to Output - From PFU	LCMXO256	—	4.0	—	4.8	—	5.6	ns
		LCMXO640	—	4.0	—	4.8	—	5.7	ns
		LCMXO1200	—	4.3	—	5.2	—	6.1	ns
		LCMXO2280	—	4.3	—	5.2	—	6.1	ns
t _{SU}	Clock to Data Setup - To PFU	LCMXO256	1.3	—	1.6	—	1.8	—	ns
		LCMXO640	1.1	—	1.3	—	1.5	—	ns
		LCMXO1200	1.1	—	1.3	—	1.6	—	ns
		LCMXO2280	1.1	—	1.3	—	1.5	—	ns
t _H	Clock to Data Hold - To PFU	LCMXO256	-0.3	—	-0.3	—	-0.3	—	ns
		LCMXO640	-0.1	—	-0.1	—	-0.1	—	ns
		LCMXO1200	0.0	—	0.0	—	0.0	—	ns
		LCMXO2280	-0.4	—	-0.4	—	-0.4	—	ns
f _{MAX_IO}	Clock Frequency of I/O and PFU Register	LCMXO256	—	600	—	550	—	500	MHz
		LCMXO640	—	600	—	550	—	500	MHz
		LCMXO1200	—	600	—	550	—	500	MHz
		LCMXO2280	—	600	—	550	—	500	MHz
t _{SKEW_PRI}	Global Clock Skew Across Device	LCMXO256	—	200	—	220	—	240	ps
		LCMXO640	—	200	—	220	—	240	ps
		LCMXO1200	—	220	—	240	—	260	ps
		LCMXO2280	—	220	—	240	—	260	ps

1. General timing numbers based on LVCMOS2.5V, 12 mA.
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MachXO Family Timing Adders^{1, 2, 3}

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25 ⁴	LVDS	0.44	0.53	0.61	ns
BLVDS25 ⁴	BLVDS	0.44	0.53	0.61	ns
LVPECL33 ⁴	LVPECL	0.42	0.50	0.59	ns
LVTTTL33	LVTTTL	0.01	0.01	0.01	ns
LVC MOS33	LVC MOS 3.3	0.01	0.01	0.01	ns
LVC MOS25	LVC MOS 2.5	0.00	0.00	0.00	ns
LVC MOS18	LVC MOS 1.8	0.07	0.08	0.10	ns
LVC MOS15	LVC MOS 1.5	0.14	0.17	0.19	ns
LVC MOS12	LVC MOS 1.2	0.40	0.48	0.56	ns
PCI33 ⁴	PCI	0.01	0.01	0.01	ns
Output Adjusters					
LVDS25E	LVDS 2.5 E	-0.13	-0.15	-0.18	ns
LVDS25 ⁴	LVDS 2.5	-0.21	-0.26	-0.30	ns
BLVDS25	BLVDS 2.5	-0.03	-0.03	-0.04	ns
LVPECL33	LVPECL 3.3	0.04	0.04	0.05	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.04	0.04	0.05	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.06	0.07	0.08	ns
LVTTTL33_12mA	LVTTTL 12mA drive	-0.01	-0.01	-0.01	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.50	0.60	0.70	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.04	0.04	0.05	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.06	0.07	0.08	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	-0.01	-0.01	-0.01	ns
LVC MOS33_14mA	LVC MOS 3.3 14mA drive	0.50	0.60	0.70	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.05	0.06	0.07	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.10	0.12	0.13	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVC MOS25_14mA	LVC MOS 2.5 14mA drive	0.34	0.40	0.47	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.11	0.13	0.15	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.05	0.06	0.06	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	-0.06	-0.07	-0.08	ns
LVC MOS18_14mA	LVC MOS 1.8 14mA drive	0.06	0.07	0.09	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.15	0.19	0.22	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.05	0.06	0.07	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.26	0.31	0.36	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.05	0.06	0.07	ns
PCI33 ⁴	PCI33	1.85	2.22	2.59	ns

1. Timing adders are characterized but not tested on every device.

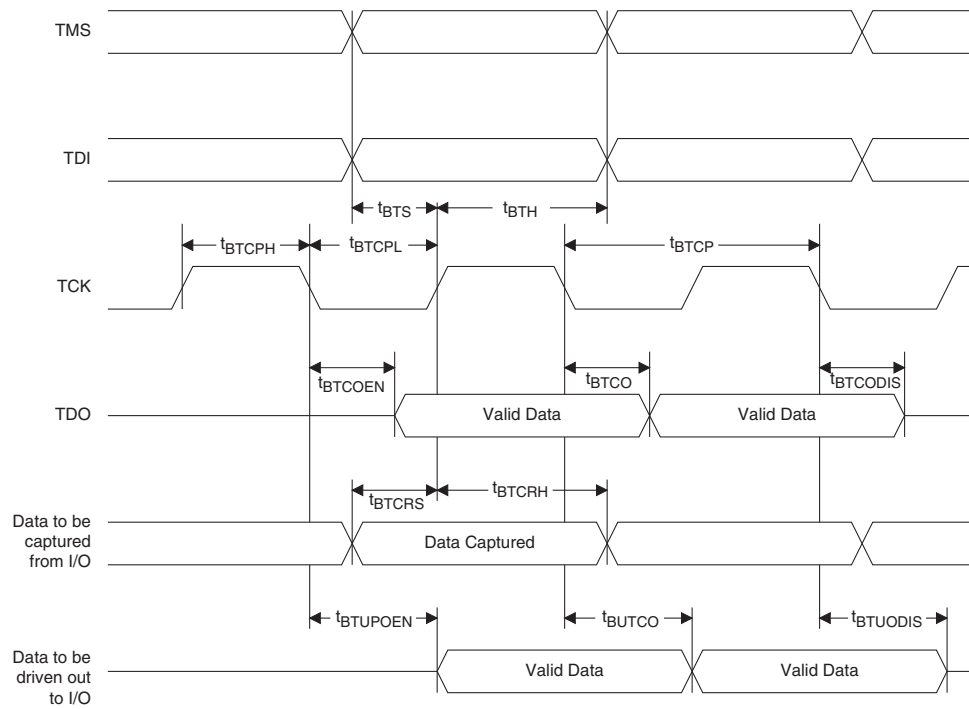
2. LVC MOS timing is measured with the load specified in Switching Test Conditions table.

3. All other standards tested according to the appropriate specifications.

4. I/O standard only available in LCMXO1200 and LCMXO2280 devices.

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Figure 3-5. JTAG Port Timing Waveforms



Pin Information Summary

Pin Type		LCMX0256C/E		LCMX0640C/E				
		100 TQFP	100 csBGA	100 TQFP	144 TQFP	100 csBGA	132 csBGA	256 caBGA / 256 ftBGA
Single Ended User I/O		78	78	74	113	74	101	159
Differential Pair User I/O ¹		38	38	17	43	17	42	79
Muxed		6	6	6	6	6	6	6
TAP		4	4	4	4	4	4	4
Dedicated (Total Without Supplies)		5	5	5	5	5	5	5
VCC		2	2	2	4	2	4	4
VCCAUX		1	1	1	2	1	2	2
VCCIO	Bank0	3	3	2	2	2	2	4
	Bank1	3	3	2	2	2	2	4
	Bank2	—	—	2	2	2	2	4
	Bank3	—	—	2	2	2	2	4
GND		8	8	10	12	10	12	18
NC		0	0	0	0	0	0	52
Single Ended/Differential I/O per Bank	Bank0	41/20	41/20	18/5	29/10	18/5	26/11	42/21
	Bank1	37/18	37/18	21/4	30/11	21/4	27/12	40/20
	Bank2	—	—	14/2	24/9	14/2	21/9	36/18
	Bank3	—	—	21/6	30/13	21/6	27/10	40/20

1. These devices support emulated LVDS outputs. LVDS inputs are not supported.

Pin Type		LCMX01200C/E				LCMX02280C/E				
		100 TQFP	144 TQFP	132 csBGA	256 caBGA / 256 ftBGA	100 TQFP	144 TQFP	132 csBGA	256 caBGA / 256 ftBGA	324 ftBGA
Single Ended User I/O		73	113	101	211	73	113	101	211	271
Differential Pair User I/O ¹		27	48	42	105	30	47	41	105	134
Muxed		6	6	6	6	6	6	6	6	6
TAP		4	4	4	4	4	4	4	4	4
Dedicated (Total Without Supplies)		5	5	5	5	5	5	5	5	5
VCC		4	4	4	4	2	4	4	4	6
VCCAUX		2	2	2	2	2	2	2	2	2
VCCIO	Bank0	1	1	1	2	1	1	1	2	2
	Bank1	1	1	1	2	1	1	1	2	2
	Bank2	1	1	1	2	1	1	1	2	2
	Bank3	1	1	1	2	1	1	1	2	2
	Bank4	1	1	1	2	1	1	1	2	2
	Bank5	1	1	1	2	1	1	1	2	2
	Bank6	1	1	1	2	1	1	1	2	2
	Bank7	1	1	1	2	1	1	1	2	2
GND		8	12	12	18	8	12	12	18	24
NC		0	0	0	0	0	0	0	0	0
Single Ended/Differential I/O per Bank	Bank0	10/3	14/6	13/5	26/13	9/3	13/6	12/5	24/12	34/17
	Bank1	8/2	15/7	13/5	28/14	9/3	16/7	14/5	30/15	36/18
	Bank2	10/4	15/7	13/6	26/13	10/4	15/7	13/6	26/13	34/17
	Bank3	11/5	15/7	14/7	28/14	11/5	15/7	14/7	28/14	34/17
	Bank4	8/3	14/5	13/5	27/13	8/3	14/4	13/4	29/14	35/17
	Bank5	5/2	10/4	8/2	22/11	5/2	10/4	8/2	20/10	30/15
	Bank6	10/3	15/6	13/6	28/14	10/4	15/6	13/6	28/14	34/17
	Bank7	11/5	15/6	14/6	26/13	11/5	15/6	14/6	26/13	34/17

1. These devices support on-chip LVDS buffers for left and right I/O Banks.

Power Supply and NC

Signal	100 TQFP ¹	144 TQFP ¹	100 csBGA ²
VCC	LCMXO256/640: 35, 90 LCMXO1200/2280: 17, 35, 66, 91	21, 52, 93, 129	P7, B6
VCCIO0	LCMXO256: 60, 74, 92 LCMXO640: 80, 92 LCMXO1200/2280: 94	LCMXO640: 117, 135 LCMXO1200/2280: 135	LCMXO256: H14, A14, B5 LCMXO640: B12, B5
VCCIO1	LCMXO256: 10, 24, 41 LCMXO640: 60, 74 LCMXO1200/2280: 80	LCMXO640: 82, 98 LCMXO1200/2280: 117	LCMXO256: G1, P1, P10 LCMXO640: H14, A14
VCCIO2	LCMXO256: None LCMXO640: 29, 41 LCMXO1200/2280: 70	LCMXO640: 38, 63 LCMXO1200/2280: 98	LCMXO256: None LCMXO640: P4, P10
VCCIO3	LCMXO256: None LCMXO640: 10, 24 LCMXO1200/2280: 56	LCMXO640: 10, 26 LCMXO1200/2280: 82	LCMXO256: None LCMXO640: G1, P1
VCCIO4	LCMXO256/640: None LCMXO1200/2280: 44	LCMXO640: None LCMXO1200/2280: 63	—
VCCIO5	LCMXO256/640: None LCMXO1200/2280: 27	LCMXO640: None LCMXO1200/2280: 38	—
VCCIO6	LCMXO256/640: None LCMXO1200/2280: 20	LCMXO640: None LCMXO1200/2280: 26	—
VCCIO7	LCMXO256/640: None LCMXO1200/2280: 6	LCMXO640: None LCMXO1200/2280: 10	—
VCCAUX	LCMXO256/640: 88 LCMXO1200/2280: 36, 90	53, 128	B7
GND ³	LCMXO256: 40, 84, 62, 75, 93, 12, 25, 42 LCMXO640: 40, 84, 81, 93, 62, 75, 30, 42, 12, 25 LCMXO1200/2280: 9, 41, 59, 83, 100, 76, 50, 26	16, 59, 88, 123, 118, 136, 83, 99, 37, 64, 11, 27	LCMXO256: N9, B9, G14, B13, A4, H1, N2, N10 LCMXO640: N9, B9, A10, A4, G14, B13, N3, N10, H1, N2
NC ⁴			—

1. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.
2. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
3. All grounds must be electrically connected at the board level. For fpBGA and ftBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
4. NC pins should not be connected to any active signals, VCC or GND.

LCMX0256 and LCMX0640 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMX0256				LCMX0640			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
43	PB4A	1		T	PB8B	2		
44	PB4B	1		C	PB8C	2		T
45	PB4C	1		T	PB8D	2		C
46	PB4D	1		C	PB9A	2		
47	PB5A	1			PB9C	2		T
48*	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
49	PB5C	1		T	PB9D	2		C
50	PB5D	1		C	PB9F	2		
51	PR9B	0		C	PR11D	1		C
52	PR9A	0		T	PR11B	1		C
53	PR8B	0		C	PR11C	1		T
54	PR8A	0		T	PR11A	1		T
55	PR7D	0		C	PR10D	1		C
56	PR7C	0		T	PR10C	1		T
57	PR7B	0		C	PR10B	1		C
58	PR7A	0		T	PR10A	1		T
59	PR6B	0		C	PR9D	1		
60	VCCIO0	0			VCCIO1	1		
61	PR6A	0		T	PR9B	1		
62	GNDIO0	0			GNDIO1	1		
63	PR5D	0		C	PR7B	1		
64	PR5C	0		T	PR6C	1		
65	PR5B	0		C	PR6B	1		
66	PR5A	0		T	PR5D	1		
67	PR4B	0		C	PR5B	1		
68	PR4A	0		T	PR4D	1		
69	PR3D	0		C	PR4B	1		
70	PR3C	0		T	PR3D	1		
71	PR3B	0		C	PR3B	1		
72	PR3A	0		T	PR2D	1		
73	PR2B	0		C	PR2B	1		
74	VCCIO0	0			VCCIO1	1		
75	GNDIO0	0			GNDIO1	1		
76	PR2A	0		T	PT9F	0		C
77	PT5C	0			PT9E	0		T
78	PT5B	0		C	PT9C	0		
79	PT5A	0		T	PT9A	0		
80	PT4F	0		C	VCCIO0	0		
81	PT4E	0		T	GNDIO0	0		
82	PT4D	0		C	PT7E	0		
83	PT4C	0		T	PT7A	0		
84	GND	-			GND	-		

LCMX01200 and LCMX02280 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMX01200				LCMX02280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
42	PB9A	4		T	PB12A	4		T
43	PB9B	4		C	PB12B	4		C
44	VCCIO4	4			VCCIO4	4		
45	PB10A	4		T	PB13A	4		T
46	PB10B	4		C	PB13B	4		C
47***	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
48	PB11A	4		T	PB16A	4		T
49	PB11B	4		C	PB16B	4		C
50**	GNDIO3 GNDIO4	-			GNDIO3 GNDIO4	-		
51	PR16B	3			PR19B	3		
52	PR15B	3		C*	PR18B	3		C*
53	PR15A	3		T*	PR18A	3		T*
54	PR14B	3		C*	PR17B	3		C*
55	PR14A	3		T*	PR17A	3		T*
56	VCCIO3	3			VCCIO3	3		
57	PR12B	3		C*	PR15B	3		C*
58	PR12A	3		T*	PR15A	3		T*
59	GND	-			GND	-		
60	PR10B	3		C*	PR13B	3		C*
61	PR10A	3		T*	PR13A	3		T*
62	PR9B	3		C*	PR11B	3		C*
63	PR9A	3		T*	PR11A	3		T*
64	PR8B	2		C*	PR10B	2		C*
65	PR8A	2		T*	PR10A	2		T*
66	VCC	-			VCC	-		
67	PR6C	2			PR8C	2		
68	PR6B	2		C*	PR8B	2		C*
69	PR6A	2		T*	PR8A	2		T*
70	VCCIO2	2			VCCIO2	2		
71	PR4D	2			PR5D	2		
72	PR4B	2		C*	PR5B	2		C*
73	PR4A	2		T*	PR5A	2		T*
74	PR2B	2		C	PR3B	2		C*
75	PR2A	2		T	PR3A	2		T*
76**	GNDIO1 GNDIO2	-			GNDIO1 GNDIO2	-		
77	PT11C	1			PT15C	1		
78	PT11B	1		C	PT14B	1		C
79	PT11A	1		T	PT14A	1		T
80	VCCIO1	1			VCCIO1	1		
81	PT9E	1			PT12D	1		C

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
51	TDI	2	TDI		TDI	5	TDI		TDI	5	TDI	
52	VCC	-			VCC	-			VCC	-		
53	VCCAUX	-			VCCAUX	-			VCCAUX	-		
54	PB5A	2		T	PB6F	5			PB8F	5		
55	PB5B	2	PCLKT2_1***	C	PB7B	4	PCLK4_1***		PB10F	4	PCLK4_1***	
56	PB5D	2			PB7C	4		T	PB10C	4		T
57	PB6A	2		T	PB7D	4		C	PB10D	4		C
58	PB6B	2	PCLKT2_0***	C	PB7F	4	PCLK4_0***		PB10B	4	PCLK4_0***	
59	GND	-			GND	-			GND	-		
60	PB7C	2			PB9A	4		T	PB12A	4		T
61	PB7E	2			PB9B	4		C	PB12B	4		C
62	PB8A	2			PB9E	4			PB12E	4		
63	VCCIO2	2			VCCIO4	4			VCCIO4	4		
64	GNDIO2	2			GNDIO4	4			GNDIO4	4		
65	PB8C	2		T	PB10A	4		T	PB13A	4		T
66	PB8D	2		C	PB10B	4		C	PB13B	4		C
67	PB9A	2		T	PB10C	4		T	PB13C	4		T
68	PB9C	2		T	PB10D	4		C	PB13D	4		C
69	PB9B	2		C	PB10F	4			PB14D	4		
70**	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
71	PB9D	2		C	PB11C	4		T	PB16C	4		T
72	PB9F	2			PB11D	4		C	PB16D	4		C
73	PR11D	1		C	PR16B	3		C	PR20B	3		C
74	PR11B	1		C	PR16A	3		T	PR20A	3		T
75	PR11C	1		T	PR15B	3		C*	PR19B	3		C
76	PR10D	1		C	PR15A	3		T*	PR19A	3		T
77	PR11A	1		T	PR14D	3		C	PR17D	3		C
78	PR10B	1		C	PR14C	3		T	PR17C	3		T
79	PR10C	1		T	PR14B	3		C*	PR17B	3		C*
80	PR10A	1		T	PR14A	3		T*	PR17A	3		T*
81	PR9D	1			PR13D	3			PR16D	3		
82	VCCIO1	1			VCCIO3	3			VCCIO3	3		
83	GNDIO1	1			GNDIO3	3			GNDIO3	3		
84	PR9A	1			PR12B	3		C*	PR15B	3		C*
85	PR8C	1			PR12A	3		T*	PR15A	3		T*
86	PR8A	1			PR11B	3		C*	PR14B	3		C*
87	PR7D	1			PR11A	3		T*	PR14A	3		T*
88	GND	-			GND	-			GND	-		
89	PR7B	1		C	PR10B	3		C*	PR13B	3		C*
90	PR7A	1		T	PR10A	3		T*	PR13A	3		T*
91	PR6D	1		C	PR8B	2		C*	PR10B	2		C*
92	PR6C	1		T	PR8A	2		T*	PR10A	2		T*
93	VCC	-			VCC	-			VCC	-		
94	PR5D	1			PR6B	2		C*	PR8B	2		C*
95	PR5B	1			PR6A	2		T*	PR8A	2		T*
96	PR4D	1			PR5B	2		C*	PR7B	2		C*
97	PR4B	1		C	PR5A	2		T*	PR7A	2		T*
98	VCCIO1	1			VCCIO2	2			VCCIO2	2		
99	GNDIO1	1			GNDIO2	2			GNDIO2	2		
100	PR4A	1		T	PR4C	2			PR5C	2		

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
101	PR3D	1		C	PR4B	2		C*	PR5B	2		C*
102	PR3C	1		T	PR4A	2		T*	PR5A	2		T*
103	PR3B	1		C	PR3D	2		C	PR4D	2		C
104	PR2D	1		C	PR3C	2		T	PR4C	2		T
105	PR3A	1		T	PR3B	2		C*	PR4B	2		C*
106	PR2B	1		C	PR3A	2		T*	PR4A	2		T*
107	PR2C	1		T	PR2B	2		C	PR3B	2		C*
108	PR2A	1		T	PR2A	2		T	PR3A	2		T*
109	PT9F	0		C	PT11D	1		C	PT16D	1		C
110	PT9D	0		C	PT11C	1		T	PT16C	1		T
111	PT9E	0		T	PT11B	1		C	PT16B	1		C
112	PT9B	0		C	PT11A	1		T	PT16A	1		T
113	PT9C	0		T	PT10F	1		C	PT15D	1		C
114	PT9A	0		T	PT10E	1		T	PT15C	1		T
115	PT8C	0			PT10D	1		C	PT14B	1		C
116	PT8B	0		C	PT10C	1		T	PT14A	1		T
117	VCCIO0	0			VCCIO1	1			VCCIO1	1		
118	GNDIO0	0			GNDIO1	1			GNDIO1	1		
119	PT8A	0		T	PT9F	1		C	PT12F	1		C
120	PT7E	0			PT9E	1		T	PT12E	1		T
121	PT7C	0			PT9B	1		C	PT12D	1		C
122	PT7A	0			PT9A	1		T	PT12C	1		T
123	GND	-			GND	-			GND	-		
124	PT6B	0	PCLK0_1***	C	PT7D	1	PCLK1_1***		PT10B	1	PCLK1_1***	
125	PT6A	0		T	PT7B	1		C	PT9D	1		C
126	PT5C	0			PT7A	1		T	PT9C	1		T
127	PT5B	0	PCLK0_0***		PT6F	0	PCLK1_0***		PT9B	1	PCLK1_0***	
128	VCCAUX	-			VCCAUX	-			VCCAUX	-		
129	VCC	-			VCC	-			VCC	-		
130	PT4D	0			PT5D	0		C	PT7B	0		C
131	PT4B	0		C	PT5C	0		T	PT7A	0		T
132	PT4A	0		T	PT5B	0		C	PT6D	0		
133	PT3F	0			PT5A	0		T	PT6E	0		T
134	PT3D	0			PT4B	0			PT6F	0		C
135	VCCIO0	0			VCCIO0	0			VCCIO0	0		
136	GNDIO0	0			GNDIO0	0			GNDIO0	0		
137	PT3B	0		C	PT3D	0		C	PT4B	0		T
138	PT2F	0		C	PT3C	0		T	PT4A	0		C
139	PT3A	0		T	PT3B	0		C	PT3B	0		C
140	PT2D	0		C	PT3A	0		T	PT3A	0		T
141	PT2E	0		T	PT2D	0		C	PT2D	0		C
142	PT2B	0		C	PT2C	0		T	PT2C	0		T
143	PT2C	0		T	PT2B	0		C	PT2B	0		C
144	PT2A	0		T	PT2A	0		T	PT2A	0		T

*Supports true LVDS outputs.

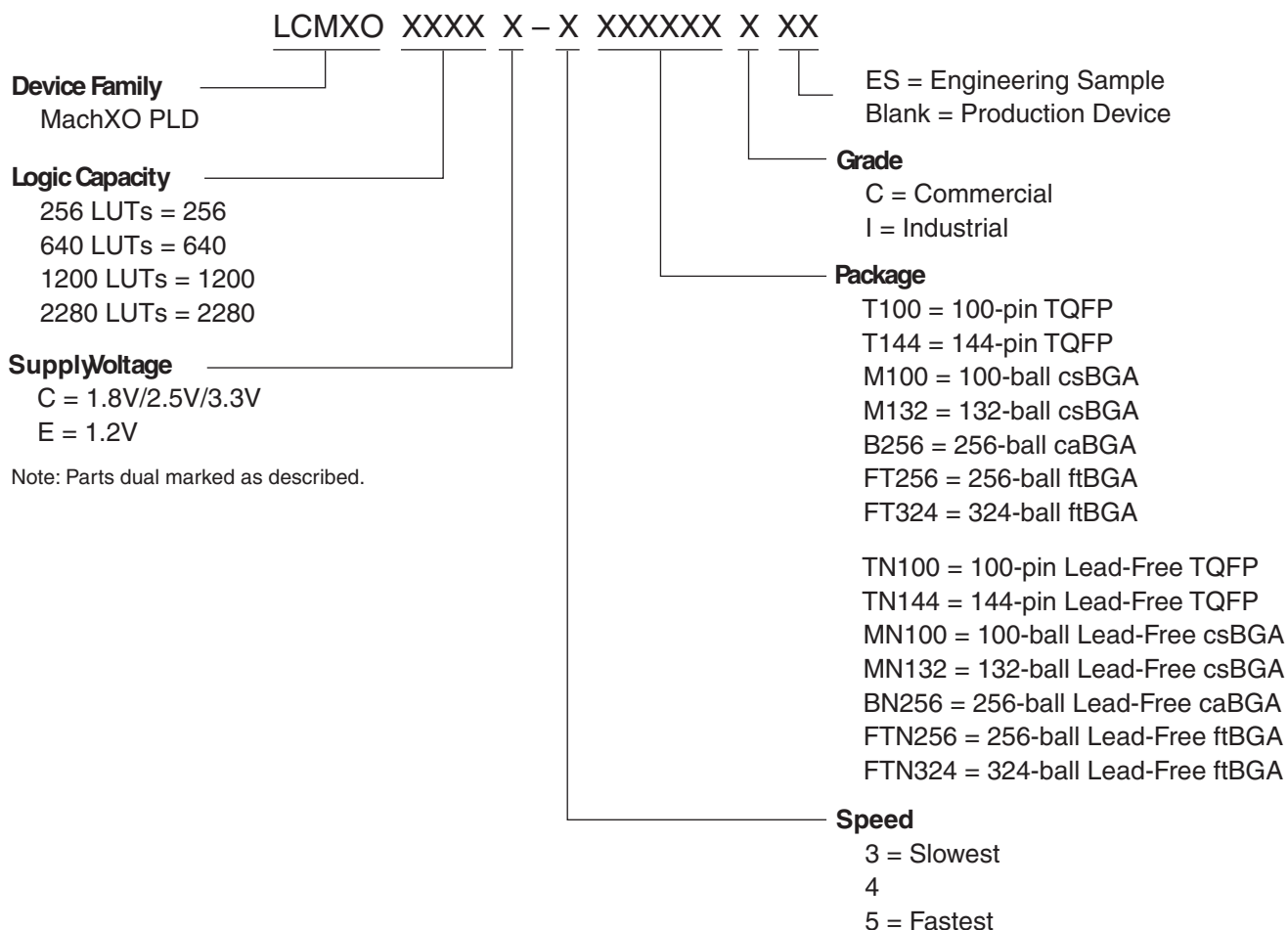
**NC for "E" devices.

***Primary clock inputs are single-ended.

LCMX02280 Logic Signal Connections: 324 ftBGA (Cont.)

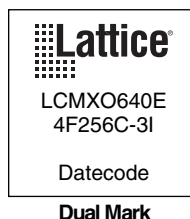
LCMX02280				
Ball Number	Ball Function	Bank	Dual Function	Differential
A10	PT8E	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
A9	PT8D	0		C
C9	PT8C	0		T
B9	PT8B	0		C
F9	VCCAUX	-		
A8	PT8A	0		T
B8	PT7D	0		C
C8	PT7C	0		T
VCC	VCC	-		
A7	PT7B	0		C
B7	PT7A	0		T
A6	PT6A	0		T
B6	PT6B	0		C
D8	PT6C	0		T
F8	PT6D	0		C
C7	PT6E	0		T
E8	PT6F	0		C
D7	PT5D	0		C
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E7	PT5C	0		T
A5	PT5B	0		C
C6	PT5A	0		T
B5	PT4A	0		T
A4	PT4B	0		C
D6	PT4C	0		T
F7	PT4D	0		C
B4	PT4E	0		T
GND	GND	-		
C5	PT4F	0		C
F6	PT3D	0		C
E5	PT3C	0		T
E6	PT3B	0		C
D5	PT3A	0		T
A3	PT2D	0		C
C4	PT2C	0		T
A2	PT2B	0		C
B2	PT2A	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E14	GND	-		

Part Number Description



Ordering Information

Note: MachXO devices are dual marked except the slowest commercial speed grade device. For example the commercial speed grade LCMXO640E-4F256C is also marked with industrial grade -3I grade. The slowest commercial speed grade does not have industrial markings. The markings appears as follows:



Lead-Free Packaging
Commercial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256C-3TN100C	256	1.8V/2.5V/3.3V	78	-3	Lead-Free TQFP	100	COM
LCMXO256C-4TN100C	256	1.8V/2.5V/3.3V	78	-4	Lead-Free TQFP	100	COM
LCMXO256C-5TN100C	256	1.8V/2.5V/3.3V	78	-5	Lead-Free TQFP	100	COM
LCMXO256C-3MN100C	256	1.8V/2.5V/3.3V	78	-3	Lead-Free csBGA	100	COM
LCMXO256C-4MN100C	256	1.8V/2.5V/3.3V	78	-4	Lead-Free csBGA	100	COM
LCMXO256C-5MN100C	256	1.8V/2.5V/3.3V	78	-5	Lead-Free csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640C-3TN100C	640	1.8V/2.5V/3.3V	74	-3	Lead-Free TQFP	100	COM
LCMXO640C-4TN100C	640	1.8V/2.5V/3.3V	74	-4	Lead-Free TQFP	100	COM
LCMXO640C-5TN100C	640	1.8V/2.5V/3.3V	74	-5	Lead-Free TQFP	100	COM
LCMXO640C-3MN100C	640	1.8V/2.5V/3.3V	74	-3	Lead-Free csBGA	100	COM
LCMXO640C-4MN100C	640	1.8V/2.5V/3.3V	74	-4	Lead-Free csBGA	100	COM
LCMXO640C-5MN100C	640	1.8V/2.5V/3.3V	74	-5	Lead-Free csBGA	100	COM
LCMXO640C-3TN144C	640	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	COM
LCMXO640C-4TN144C	640	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	COM
LCMXO640C-5TN144C	640	1.8V/2.5V/3.3V	113	-5	Lead-Free TQFP	144	COM
LCMXO640C-3MN132C	640	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	COM
LCMXO640C-4MN132C	640	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	COM
LCMXO640C-5MN132C	640	1.8V/2.5V/3.3V	101	-5	Lead-Free csBGA	132	COM
LCMXO640C-3BN256C	640	1.8V/2.5V/3.3V	159	-3	Lead-Free caBGA	256	COM
LCMXO640C-4BN256C	640	1.8V/2.5V/3.3V	159	-4	Lead-Free caBGA	256	COM
LCMXO640C-5BN256C	640	1.8V/2.5V/3.3V	159	-5	Lead-Free caBGA	256	COM
LCMXO640C-3FTN256C	640	1.8V/2.5V/3.3V	159	-3	Lead-Free ftBGA	256	COM
LCMXO640C-4FTN256C	640	1.8V/2.5V/3.3V	159	-4	Lead-Free ftBGA	256	COM
LCMXO640C-5FTN256C	640	1.8V/2.5V/3.3V	159	-5	Lead-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200C-3TN100C	1200	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	COM
LCMXO1200C-4TN100C	1200	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	COM
LCMXO1200C-5TN100C	1200	1.8V/2.5V/3.3V	73	-5	Lead-Free TQFP	100	COM
LCMXO1200C-3TN144C	1200	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	COM
LCMXO1200C-4TN144C	1200	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	COM
LCMXO1200C-5TN144C	1200	1.8V/2.5V/3.3V	113	-5	Lead-Free TQFP	144	COM
LCMXO1200C-3MN132C	1200	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	COM
LCMXO1200C-4MN132C	1200	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	COM
LCMXO1200C-5MN132C	1200	1.8V/2.5V/3.3V	101	-5	Lead-Free csBGA	132	COM
LCMXO1200C-3BN256C	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	COM
LCMXO1200C-4BN256C	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	COM
LCMXO1200C-5BN256C	1200	1.8V/2.5V/3.3V	211	-5	Lead-Free caBGA	256	COM
LCMXO1200C-3FTN256C	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	COM
LCMXO1200C-4FTN256C	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	COM
LCMXO1200C-5FTN256C	1200	1.8V/2.5V/3.3V	211	-5	Lead-Free ftBGA	256	COM

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
October 2005	01.1	Introduction	Distributed RAM information in family table updated. Added footnote 1 - fpBGA packaging to the family selection guide.
		Architecture	sysIO Buffer section updated.
			Hot Socketing section updated.
			Sleep Mode section updated.
			SLEEP Pin Characteristics section updated.
			Oscillator section updated.
			Security section updated.
		DC and Switching Characteristics	Recommended Operating Conditions table updated.
			DC Electrical Characteristics table updated.
			Supply Current (Sleep Mode) table added with LCMXO256/640 data.
			Supply Current (Standby) table updated with LCMXO256/640 data.
			Initialization Supply Current table updated with LCMXO256/640 data.
			Programming and Erase Flash Supply Current table updated with LCMXO256/640 data.
			Register-to-Register Performance table updated (rev. A 0.16).
			External Switching Characteristics table updated (rev. A 0.16).
			Internal Timing Parameter table updated (rev. A 0.16).
			Family Timing Adders updated (rev. A 0.16).
			sysCLOCK Timing updated (rev. A 0.16).
			MachXO "C" Sleep Mode Timing updated (A 0.16).
			JTAG Port Timing Specification updated (rev. A 0.16).
		Pinout Information	SLEEPIN description updated.
			Pin Information Summary updated.
			Power Supply and NC Connection table has been updated.
			Logic Signal Connection section has been updated to include all devices/packages.
		Ordering Information	Part Number Description section has been updated.
			Ordering Part Number section has been updated (added LCMXO256C/LCMXO640C "4W").
		Supplemental Information	MachXO Density Migration Technical Note (TN1097) added.
November 2005	01.2	Pinout Information	Added "Power Supply and NC Connections" summary information for LCMXO1200 and LCMXO2280 in 100 TQFP package.
December 2005	01.3	DC and Switching Characteristics	Supply Current (Standby) table updated with LCMXO1200/2280 data.
		Ordering Information	Ordering Part Number section updated (added LCMXO2280C "4W").
April 2006	02.0	Introduction	Introduction paragraphs updated.
		Architecture	Architecture Overview paragraphs updated.